

DATA SHEET

SUNGMUN CODE : QDR-16H
DESCRIPTION : ROTARY DIP SWITCH

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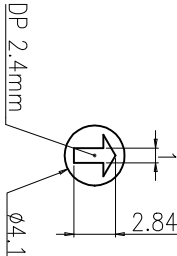
REV. NO.	DATE	REVISION	DR	CH	APP
	2026-01-12	Recreation of drawings for unification of drawing formats	M.W SHIN	K.N KIM	W.J LEE

SPECIFICATION

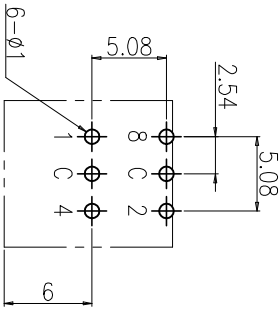
1. Rating : 150mA, DC 42V (Switching)
200mA, DC 42V (None-Switching)
2. Contact Resistance : 80mΩ Max
3. Insulation Resistance : 100MΩ Min at DC 250V
4. Operating Force : 700gf·cm Max
5. Life cycle : 10,000 steps
6. Sealing : IP67 (Dust & Water proof)
7. Packing : 50pcs Tube

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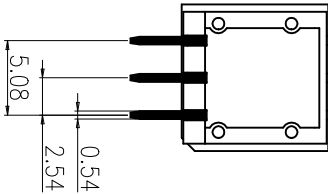
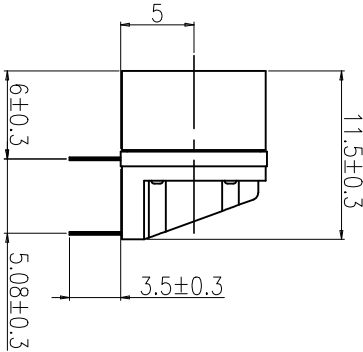
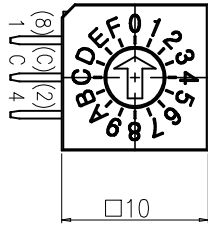
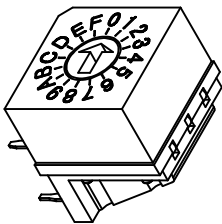
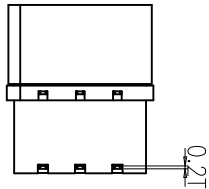
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ACTUATOR



P.C.B DIMENSION (Top View)



DRAW/DESIGNED	CHECKED	APPROVED		G.TOL	TITLE	REV.
J.S YANG	W.J LEE	K.J LEE		--	ROTARY DIP SWITCH	
			UNIT	SCALE	MODEL	
			mm	N:S	NO.	
			SIZE		DRAW	
			A4		NO.	
			QDR-16H-05			05

Din ISO-2768-1m

Ranges	0.5-3	3-6	6-30	30-120	120-400
Tolerance	± 0.1	± 0.1	± 0.2	± 0.3	± 0.5

SUNGMUN ELECTRONICS CO.,LTD

ROTARY DIP SWITCH SPECIFICATION (10X10)

Rev. 08
P : 1 / 4

1. Description:

This specification describes "10X10 size of Rotary Dip Switches" which are S, T, F and Q,E series.

1-1 Operating / Storage Temperature Range : -40°C ~ +85°C

2. Rating:

2-1 None-Switching : 200 mA, DC 42V

2-2 Switching : 150 mA, DC 42V

3. Type of Actuation : Rotating

4. Electrical Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
4-1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.
4-2	Contact Resistance	① To be measured between the two terminals associated with each switch pole. ② Measurements shall be made with a 1kHz shall current contact resistance meter.	80mΩ max.
4-3	Insulation Resistance	250V DC, 1minute ±5seconds	100 MΩ min.
4-4	Dielectric withstanding Voltage	250V AC(50Hz or 60Hz)shall be applied between all the adjacent terminal and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.

5. Mechanical Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
5-1	Operation Force	Operating direction shall be clockwise or counter clockwise direction	700gf·cm max
5-2	Operation Life	Measurements shall be made following the test set forth below: 1)150mA, 42V DC resistive load 2)Rate of operation: 15~20 cycles/ minute 3)Step of operation: 10,000 steps	1)As shown in item 4-3, 4-4 2)Contact Resistance: 200mΩ max

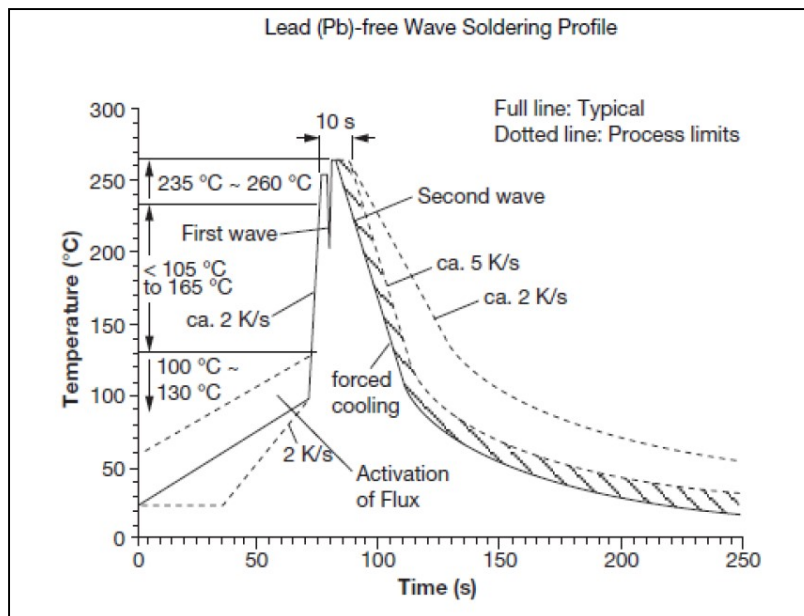
6. Environmental Characteristics

ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS
6-1	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -40°C ±3°C 2)Time: 96 hours	1)As shown in item 4-3, 4-4, 5-1 2)Contact Resistance: 200mΩ max
6-2	Resistance High Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 85°C ±2°C 2)Time: 96 hours	1)As shown in item 4-3, 4-4, 5-1 2)Contact Resistance: 200mΩ max
6-3	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40°C ±2°C 2)Relative humidity: 90~95% 3)Time: 96 hours	1)As shown in item 4-4, 5-1 2)Contact Resistance: 200mΩ max 3)Insulation Resistance: 10 MΩ min

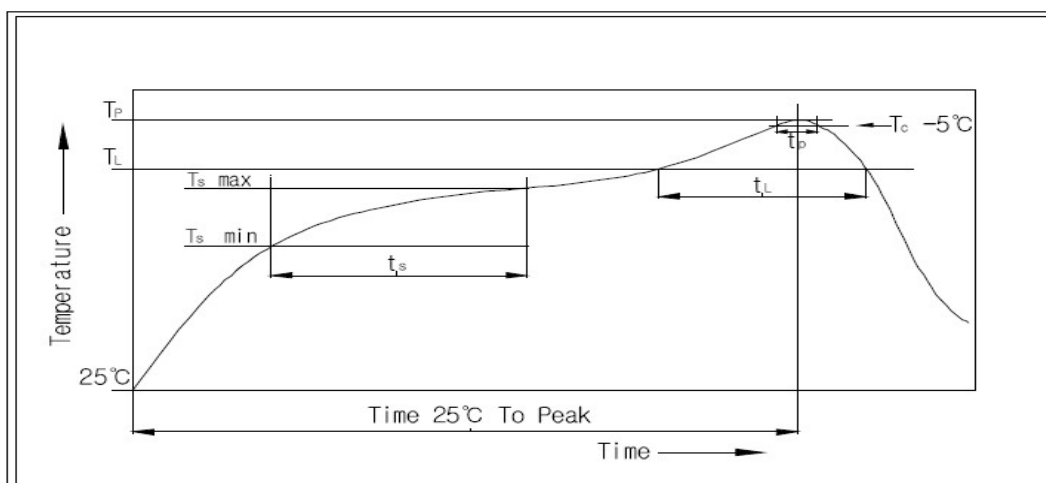
7. This item is "RoHS" Compliant

8. Manual Soldering : Max 350°C, 3 sec.

9. Wave Soldering Conditions:



10. Reflow Soldering Conditions: (SMD type only)



10-1 Condition for Soldering

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Ts max to TP)	3°C/second max
Preheat	
- Temperature Min(Ts min)	150°C
- Temperature Max(Ts max)	200°C
- Time (ts min to ts max)	60-180seconds
Time maintained above:	
- Temperature (TL)	217°C
- Time (tL)	60-150seconds
Peak/Classification Temperature(TP)	260°C +0°C/ -5°C
Time within 5°C of actual Peak Temperature(TP)	5~10 seconds
Ramp-Down Rate	6°C/sec max
Time 25°C to Peak Temperature	8 minutes max